

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

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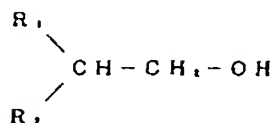
APPLICATION DATE : 15-05-87  
APPLICATION NUMBER : 62119366

APPLICANT : NIPPON GENMA:KK;

INVENTOR : OGURA TOSHIKI;

INT.CL. : B23K 35/22

TITLE : CREAMY SOLDER



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(式中、 $R_1$ は側鎖を有することもある炭素原子数1～20のアルキル基を示し、 $R_2$ は側鎖を有することもある炭素原子数6～20のアルキル基を示す。但し、 $R_1$ と $R_2$ を含むアルコールの全炭素原子数は10以上である。)

ABSTRACT : PURPOSE: To improve the reliability of a solder and solderability by contg. the alcohol of specific structure and/or its derivative.

CONSTITUTION: The alcohol condensation of an aldehyde obtd. by the hydrogenation or oxoreaction of an oxoreaction product with the olefin of an ethylene, propylene, etc., as the raw material or the alcohol expressed by an equation I with the hydrogenation of a croton condensation compound or its derivative is obtd. This alcohol or its derivative is blended at the rate of about 2~80wt.% of a creamy solder flux and a powder solder is further blended with kneading to form a creamy solder. The flux blending amt. of this case is taken at about 8~16%. Due to the alcohol or its derivative components in the flux having less change in the lapse of time and improving solderability the reliability of the solder and solderability are improved.

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<p>98-346007/30 L03 M23 ELEC= 93.08.17  ELECTROMECH RES INST *RU 2096152-C1  93.08.17 93RU-041308 (97.11.20) B23K 35/363  <b>Flux composition for low temperature brazing requiring no residues washing - containing mixture of mono:basic and di:basic organic acids that are poorly soluble in water</b>  <b>C98-106720</b>  Addnl. Data: TRYAPITSINA A N, MOSKVINA I A</p>	<p>L(3-H4E6) M(23-A2)</p> <p>Also claimed is a flux composition containing polyoxyethylated esters of lauric acid oleic acids having a mean molecular mass of 596 and 503 respectively, or polyoxyethylated aliphatic 10-18C alcohols having a molecular mass of 1000, at a concentration of &lt;0.25 wt. %.</p>
<p>The flux composition relates to fluxes used in the low temperature mechanised brazing of printed circuit boards (PCBs) using tin-lead (Sn-Pb) solders, and contains an activator containing a mixture of organic acids having 4-10C, a thickening agent and a solvent. The novelty of the flux composition is that it may also contain benzotriazole, and in that the mixture of organic acids may be a mixture of mono- and di-basic organic acids that are poorly soluble in H<sub>2</sub>O, and in that the thickening agent may be a natural or synthetic resin, and in that the solvent may be a monoatomic alcohol or its mixture with ethylacetate or triacetin. Under these conditions, the flux composition may contain (wt. %) the mixture of organic acids 3.5-6.0, the thickening agent &lt;5, the benzotriazole 0.1-0.5 and the solvent the remainder.</p>	<p><u>USE</u>  Used as the flux composition used in the low temperature brazing.</p> <p><u>ADVANTAGE</u>  Improves the brazing quality, reduces corrosive effects on Cu and eliminates the requirement to remove flux residues after the brazing.</p> <p><u>EMBODIMENT</u>  The benzotriazole is added to the flux composition as a corrosion inhibitor.  (Spp1565DwgNo.0/0)</p> <p>RU 2096152-C</p>